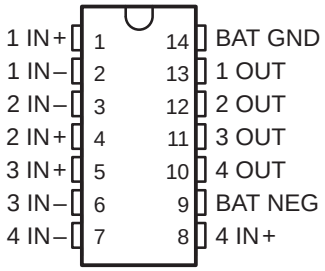
- **Designed for –52-V Battery Operation**
- **50-mA Output Current Capability**
- **Input Compatible With TTL and CMOS**
- **High Common-Mode Input Voltage Range**
- **Very Low Input Current**
- **Fail-Safe Disconnect Feature**
- **Built-in Output Clamp Diode**
- **Direct Replacement for National DS3680 and Fairchild μA3680**

D OR N PACKAGE
(TOP VIEW)

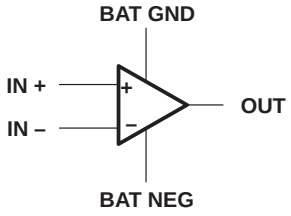


description

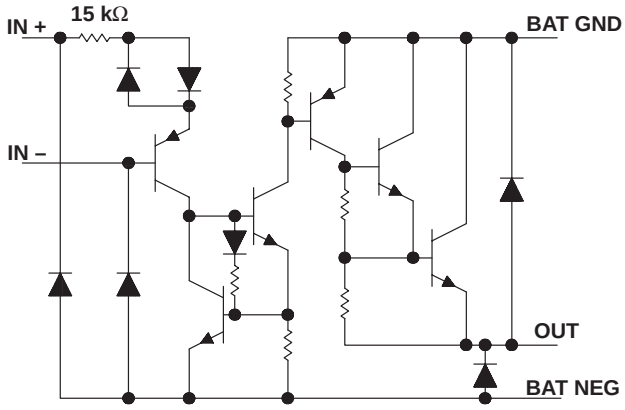
The DS3680 telephone relay driver is a monolithic integrated circuit designed to interface –48-V relay systems to TTL or other systems in telephone applications. It is capable of sourcing up to 50 mA from standard –52-V battery power. To reduce the effects of noise and IR drop between logic ground and battery ground, these drivers are designed to operate with a common-mode input range of ±20 V referenced to battery ground. The common-mode input voltages for the four drivers can be different, so a wide range of input elements can be accommodated. The high-impedance inputs are compatible with positive TTL and CMOS levels or negative logic levels. A clamp network is included in the driver outputs to limit high-voltage transients generated by the relay coil during switching. The complementary inputs ensure that the driver output is off as a fail-safe condition when either output is open.

The DS3680 is characterized for operation from 0°C to 70°C.

symbol (each driver)



schematic diagram (each driver)



All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range at BAT NEG, V_{BAT-} (see Note 1) . . . . . –70 V to 0.5 V
Input voltage range with respect to BAT GND . . . . . –70 V to 20 V
Input voltage range with respect to BAT NEG . . . . . –0.5 V to 70 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±20 V
Output current, I_O: Resistive load . . . . . –100 mA
Inductive load . . . . . –50 mA
Inductive output load . . . . . 5 H
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds . . . . . 260°C

NOTES: 1. All voltages are with respect to BAT GND, unless otherwise specified.
2. Differential input voltages are at the noninverting input terminal IN+ with respect to the inverting input terminal IN–.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{BAT-}	–10	–60	V
Input voltage, either input	–20†	20	V
High-level differential input voltage, V_{IDH}	2	20	V
Low-level differential input voltage, V_{IDL}	–20†	0.8	V
Operating free-air temperature, T_A	0	70	°C

† The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for input voltage levels.

electrical characteristics over recommended operating free-air temperature range, V_{BAT-} = –52 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP‡	MAX	UNIT
I_{IH}	High-level input current (into IN+)	V_{ID} = 2 V			40	100	µA
		V_{ID} = 7 V			375	1000	
I_{IL}	Low-level input current (into IN+)	V_{ID} = 0.4 V			0.01	5	µA
		V_{ID} = – 7 V			–1	–100	
$V_{O(on)}$	On-stage output voltage	I_O = 50 mA,	V_{ID} = 2 V		–1.6	–2.1	V
$I_{O(off)}$	Off-stage output current	$V_O = V_{BAT-}$	V_{ID} = 0.8 V		–2	–100	µA
			Inputs open		– 2	–100	
I_R	Clamp diode reverse current	V_O = 0			2	100	µA
V_{OK}	Output clamp voltage	I_O = 50 mA			0.9	1.2	V
		I_O = –50 mA,	V_{BAT-} = 0		–0.9	–1.2	
$I_{BAT(on)}$	On-state battery current	All drivers on			–2	–4.4	mA
$I_{BAT(off)}$	Off-state battery current	All drivers off			–1	–100	µA

‡ All typical values are at T_A = 25°C.

switching characteristics $V_{BAT–}$ = –52 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{on}	Turn-on time	V_{ID} = 3-V pulse, R_L = 1 kΩ, L = 1 H, See Figure 2		1	10	µs
t_{off}	Turn-off time			1	10	µs

PARAMETER MEASUREMENT INFORMATION

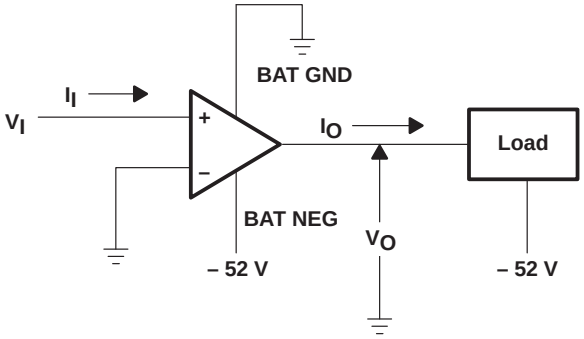


Figure 1. Generalized Test Circuit, Each Driver

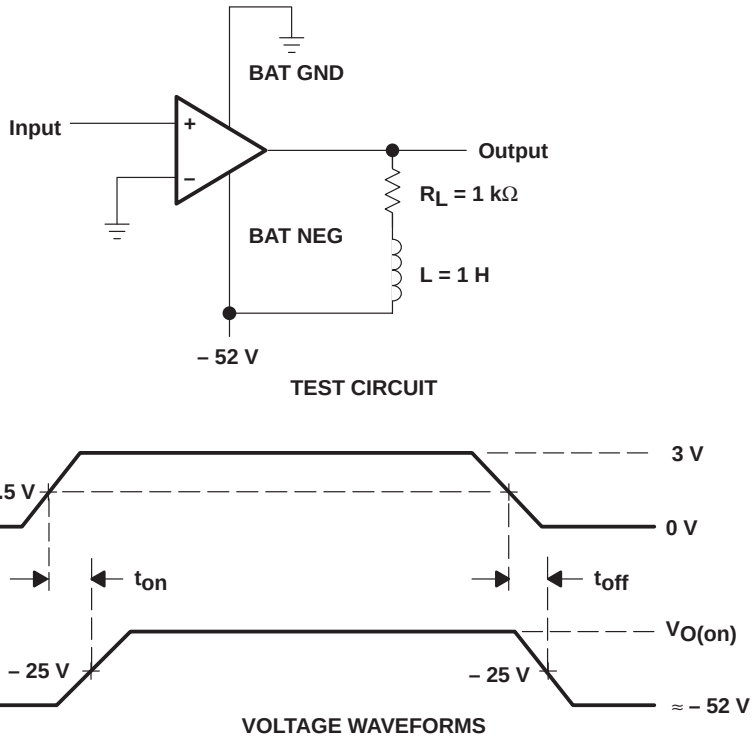


Figure 2. Test Circuit and Voltage Waveforms, Each Driver

APPLICATION INFORMATION

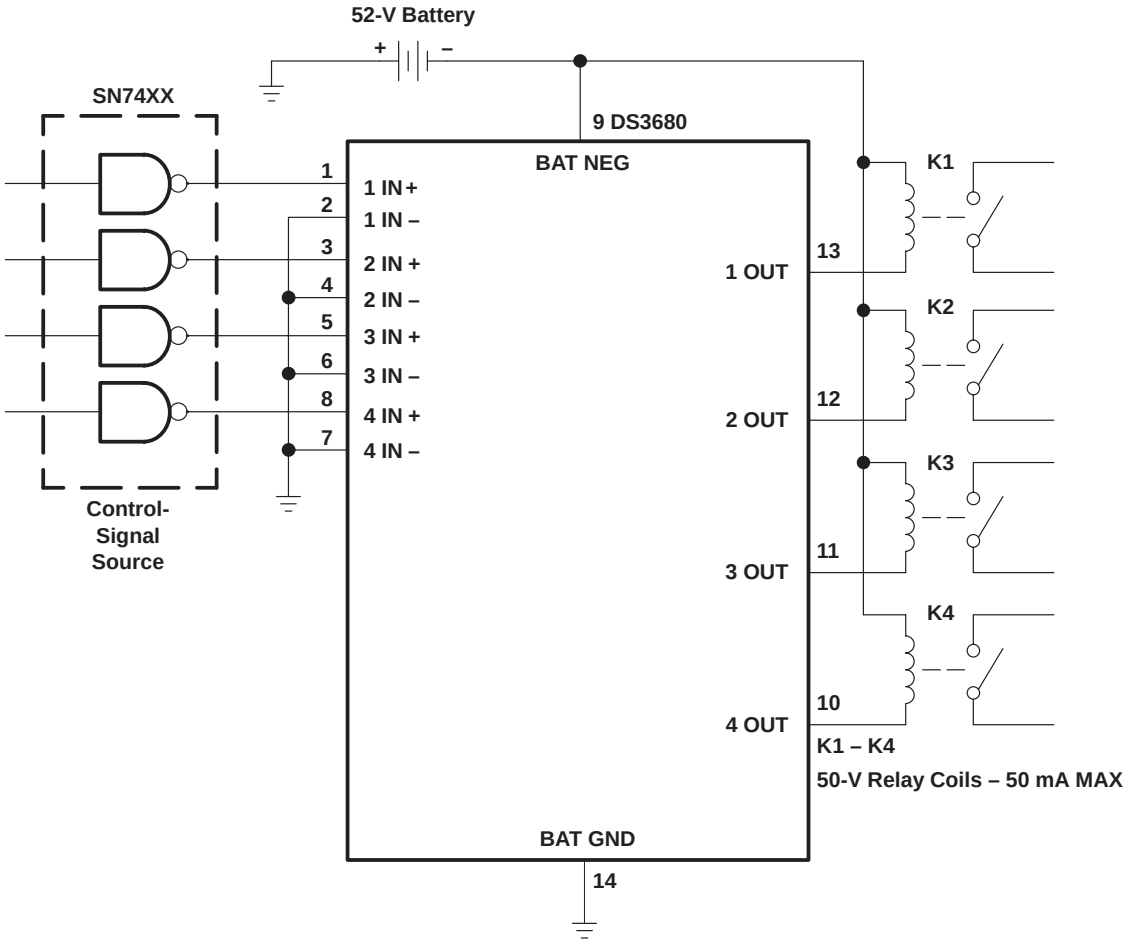


Figure 3. Relay Driver

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS3680D	Active	Production	SOIC (D) | 14	50 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS3680
DS3680D.A	Active	Production	SOIC (D) | 14	50 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS3680
DS3680DE4	Active	Production	SOIC (D) | 14	50 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS3680
DS3680N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	DS3680N
DS3680N.A	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	DS3680N

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

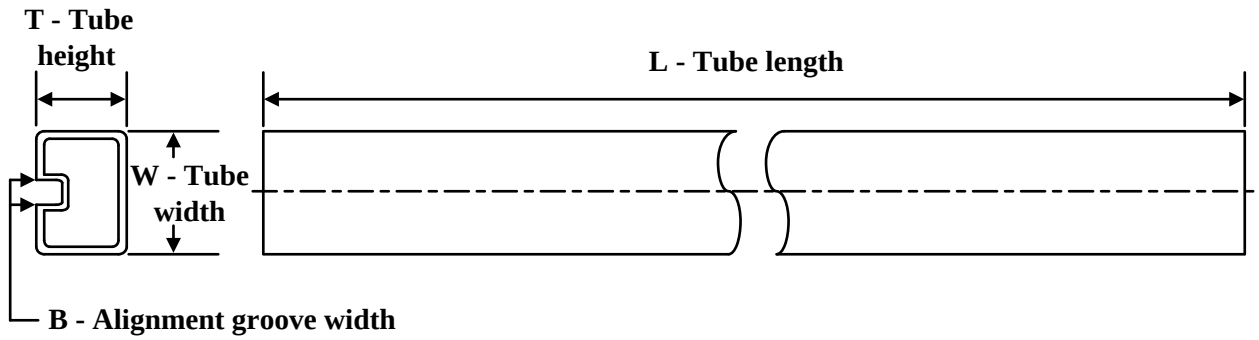
(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

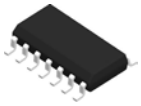
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
DS3680D	D	SOIC	14	50	506.6	8	3940	4.32
DS3680D.A	D	SOIC	14	50	506.6	8	3940	4.32
DS3680DE4	D	SOIC	14	50	506.6	8	3940	4.32
DS3680N	N	PDIP	14	25	506	13.97	11230	4.32
DS3680N.A	N	PDIP	14	25	506	13.97	11230	4.32

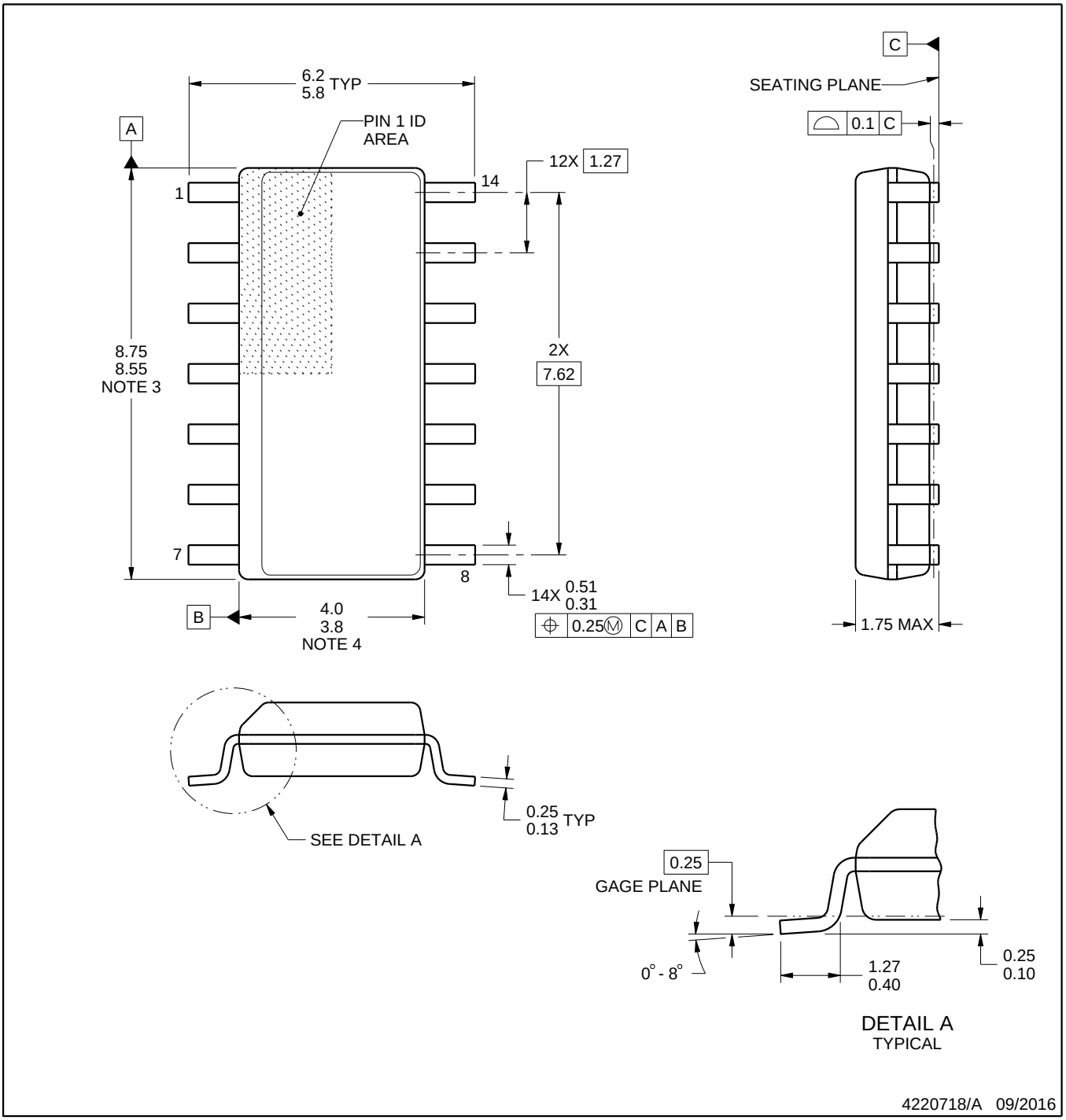


PACKAGE OUTLINE

D0014A

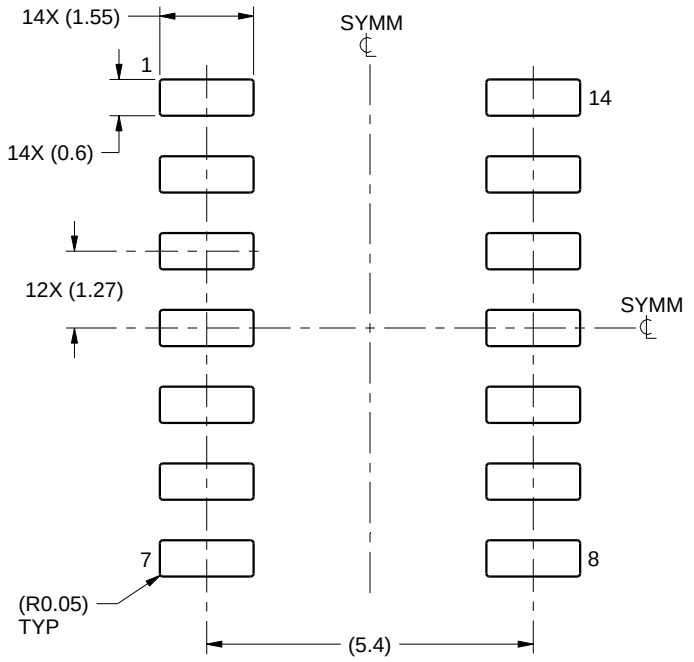
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

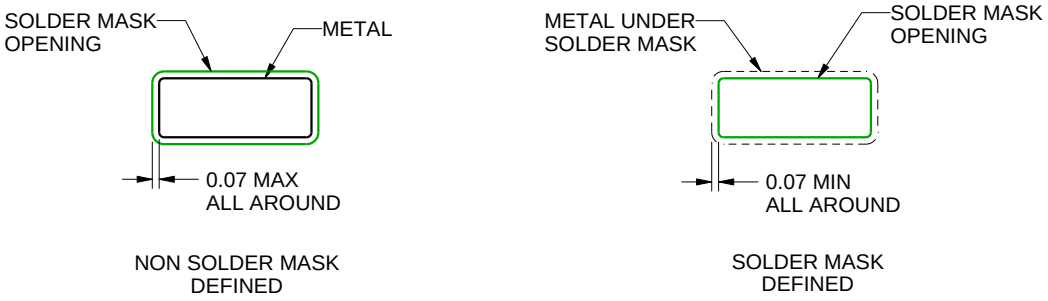


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

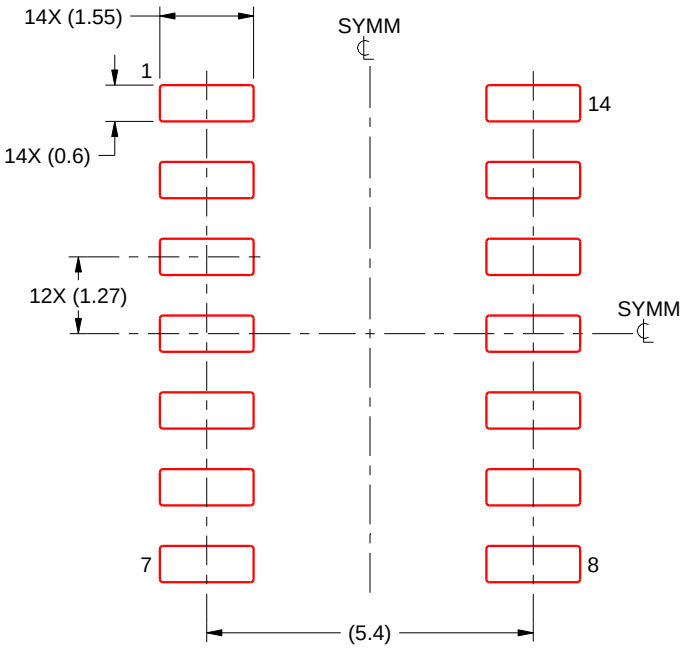
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

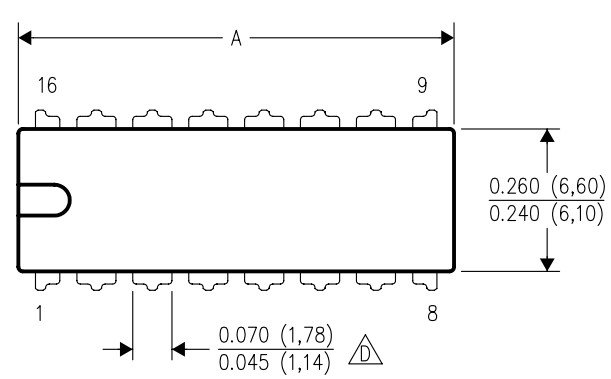
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

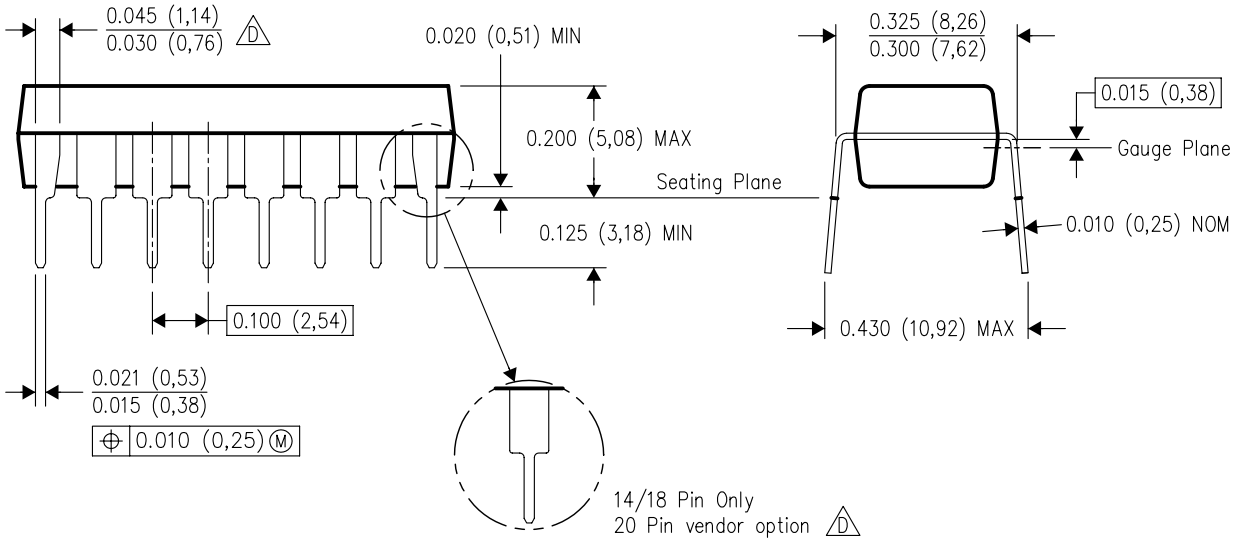
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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